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07-05-2002
102144169
PATENT

Our Ref.: 900-433

Commissioner of Patents and Trademarks
Box Assignment, Washington, D.C. 20231

To the Honorable Commissioner of Patents and Trademarks: Please record the attached original documents or copy thereof.

1. Name of conveying party(ies):

Yoshihiko MATSUO
Ryukichi IKEDA
Kimihiko YOSHIDA
Fumio OKUDA

6-25-02

2. Name and address of receiving party(ies):

Name: Sharp Kabushiki Kaisha
Internal Address:
Street Address: 22-22, Nagaike-cho, Abeno-ku

City: Osaka-shi, Osaka
State/Country: Japan
Zip: 545-8522

11046 U.S. PTO
10/178304
06/25/02

Additional name/s of conveying party/ies attached?

3. Nature of conveyance:

- Assignment Merger
- Security Assignment Change of Name
- Other _____

Execution Date: May 29, 2002, May 31, 2002, May 31, 2002 and May 31, 2002, respectively

Additional name/s & address/es attached? Yes No

4. Application number(s) or patent number(s):

If this document is being filed together with a new application, the execution date of the application is:

May 29, 2002, May 31, 2002, May 31, 2002 And May 31, 2002, Respectively

10/178304

A. Patent Application No(s).

- (1) to be assigned
- (2)
- (3)

B. Patent No(s).

- (1)
- (2)
- (3)

Additional numbers attached Yes No

5. Name and address of party to whom correspondence concerning document should be mailed:

Name: H. Warren Burnam, Jr.

Internal Address: _____

Street Address: Nixon & Vanderhye P.C.
1100 North Glebe Road
8th Floor

City: Arlington State: VA Zip: 22201

6. Total number of applications & patents involved: 1

7. Total fee (37 CFR 3.41) \$ 40.00

- Enclosed
- Authorized to be charged to deposit account #14-1140

8. The Commissioner is hereby authorized to charge any deficiency, or credit any overpayment, in the fee(s) filed, or asserted to be filed, or which should have been filed herewith (or with any paper thereafter filed in this application by this firm) to our **Account No. 14-1140**.

DO NOT USE THIS SPACE

9. Statements and signature.

To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.

H. Warren Burnam, Jr.
Name of Person Signing
Reg. No. 29,366

H. Warren Burnam, Jr.
Signature

June 25, 2002
Date

Total number of pages including **original** cover sheet, attachments, and document: [4]

07/01/2002 WBSFAM1 00000032 10178304

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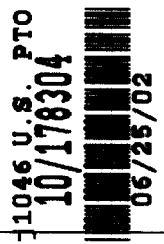
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RECORDATION FORM COVER SHEET

PATENTS ONLY

Our Ref: 900-433

Commissioner of Patents and Trademarks
Box Assignment, Washington, D.C. 20231

1. Name of conveying party(ies):	
	
2. Name: Leadmikk, Ltd Street Address: 2-2-1, Komorie, Moji-ku City: Kita Kyushu-shi, Fukuoka State: Japan Zip: 800-0007	
4. Application number(s) or patent number(s):	
A. Patent Application No(s).	B. Patent No(s).
(4)	(4)
(5)	(5)
(6)	(6)
(7)	(7)
(8)	(8)
(9)	(9)

ASSIGNMENT OF U.S. PATENT APPLICATION

Yoshihiko MATSUO, Ryukichi IKEDA, Kimihiko YOSHIDA and Fumio OKUDA

(Inventors)

In consideration of the sum of one dollar (\$1.00) and other good and valuable considerations paid to each of the undersigned, the undersigned agree(s) to assign, and hereby does assign, transfer and set over to

(Assignee) SHARP KABUSHIKI KAISHA a corporation of Japan

(Address) 22-22, Nagaike-cho, Abeno-ku, Osaka-shi, Osaka 545-8522 Japan

(Assignee) LEADMIKK, LTD. a corporation of Japan

(Address) 2-2-1, Komorie, Moji-ku, Kita Kyushu-shi, Fukuoka 800-0007 Japan

(Title) (hereinafter designated as the Assignee) the undersigned's entire right, title and interest for the United States, its territories, dependencies and possessions in the invention, and all applications for patent and any Letters Patent which may be granted therefore, known as Method for Forming Plating Film and Electronic Component Having Plating Film Formed Thereon by Same Method

for which the undersigned has (have) executed on even date herewith an application for patent in the United States of America or, if not on even date, then has executed on _____ or has already filed U.S. application Serial No. _____, on _____.

The undersigned acknowledges an obligation of assignment of this invention to said assignee at the time the invention was made.

The undersigned agree(s) to execute all papers and documents necessary in connection with the application or any interference which may be declared and any continuing or divisional applications thereof and also to execute separate assignments in connection with such applications as the Assignee may deem necessary or expedient and further to perform any act which may be necessary in connection with claims or provisions of the International Convention for Protection of Industrial Property or similar agreements.

The undersigned agree(s) to perform all affirmative acts which may be necessary to obtain a grant of a valid United States patent to the Assignee.

The undersigned hereby authorize(s) and request(s) the Commissioner of Patents to issue any and all Letters Patent of the United States resulting from said application or any division or divisions or continuing applications thereof to the said Assignee, as Assignee of the entire interest, and hereby covenants that he has (they have) full right to convey the entire interest herein assigned, and that he has (they have) not executed and will not execute, any agreement in conflict herewith.

The undersigned hereby grant(s) the firm of NIXON & VANDERHYE P.C. the power to insert on this assignment any further identification which may be necessary or desirable in order to comply with the rules of the United States Patent Office for recordation of this document. It is understood and agreed that ASSIGNEE'S attorneys Nixon & Vanderhye P.C. have represented only ASSIGNEE and will continue to represent only ASSIGNEE with respect to this invention.

In witness whereof, executed by the undersigned on the date(s) opposite the undersigned signature(s).

Date May 29, 2002 Signature of inventor

Yoshihiko Matsuo

Yoshihiko MATSUO

Date _____ Signature of inventor

Ryukichi IKEDA

Date _____ Signature of inventor

Kimihiko YOSHIDA

Date _____ Signature of inventor

Fumio OKUDA

Date _____ Signature of inventor

Witnessed by: _____

Date _____

FOR ADDITIONAL INVENTORS, check box and attach sheet with same information and signature and date for each.

ASSIGNMENT OF U.S. PATENT APPLICATION

Yoshihiko MATSUO, Ryukichi IKEDA, Kimihiko YOSHIDA and Fumio OKUDA

(Inventors)

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(Assignee)

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(Address)

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(Title)

(hereinafter designated as the Assignee) the undersigned's entire right, title and interest for the United States, its territories, dependencies and possessions in the invention, and all applications for patent and any Letters Patent which may be granted therefore, known as Method for Forming Plating Film and Electronic Component Having Plating Film Formed Thereon by Same Method

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In witness whereof, executed by the undersigned on the date(s) opposite the undersigned signature(s).

Date _____ Signature of inventor

Yoshihiko MATSUO

Date _____ Signature of inventor

Ryukichi IKEDA

Ryukichi Ikeda

Date May 31, 2002 Signature of inventor

Kimihiko YOSHIDA

Kimihiko Yoshida

Date May 31, 2002 Signature of inventor

Fumio OKUDA

Fumio Okuda

Date May 31, 2002 Signature of inventor

Witnessed by: _____

Date _____